

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V _{DSS}	12	V
Gate-Source Voltage			V _{GSS}	±8	V
Continuous Drain Current (Note 6) V _{GS} = 4.5V	Steady State	T _A = +25°C T _A = +70°C	I _D	9.3 7.4	A
	t < 10s	T _A = +25°C T _A = +70°C	I _D	11 8.8	A
Pulsed Drain Current (10µs pulse, duty cycle = 1%)			I _{DM}	70	A
Maximum Body Diode Forward Current (Note 6)			I _S	2	A

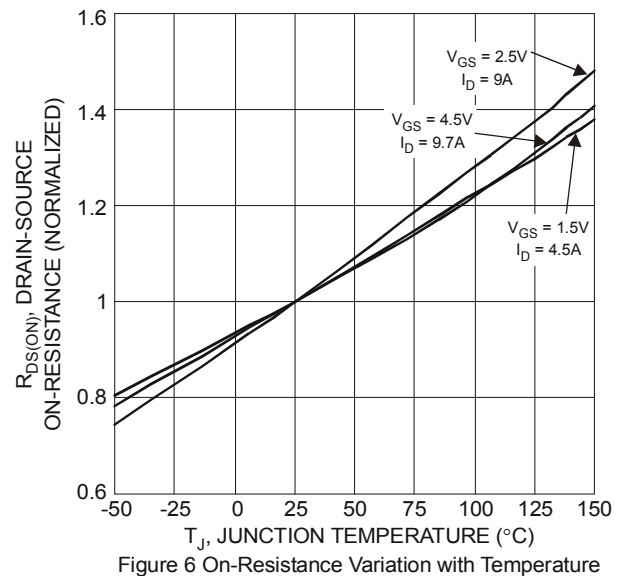
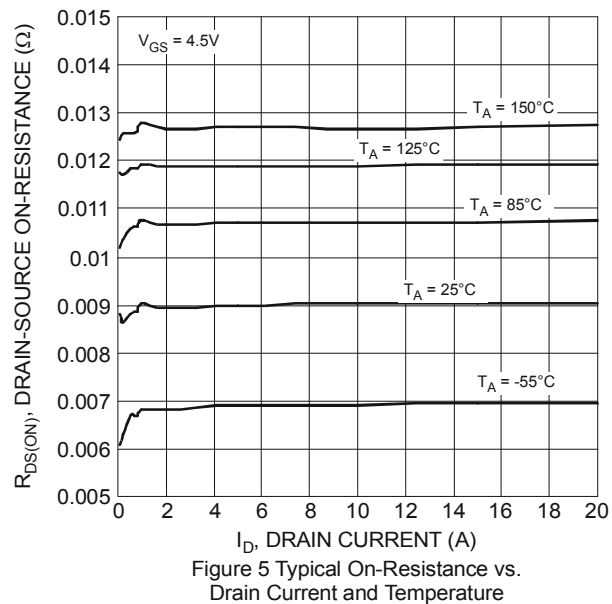
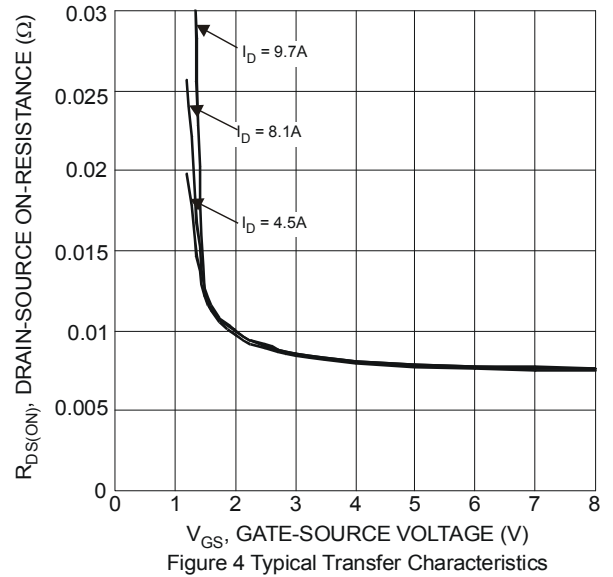
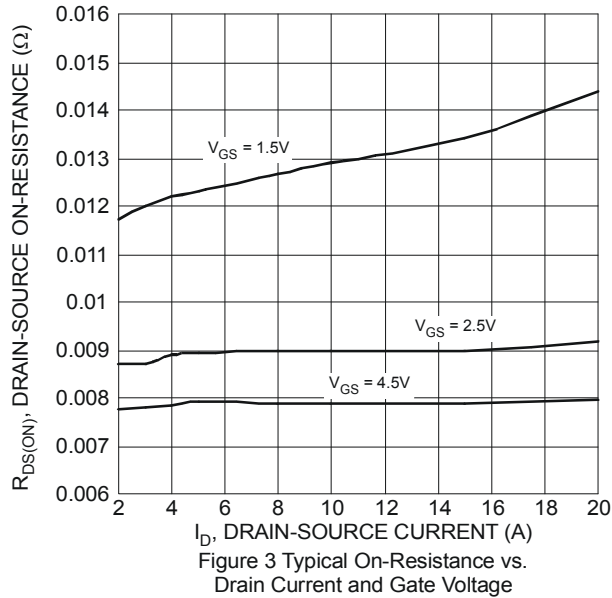
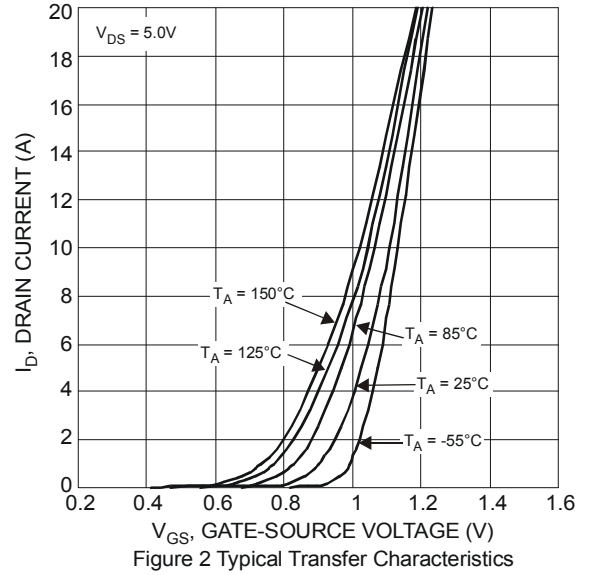
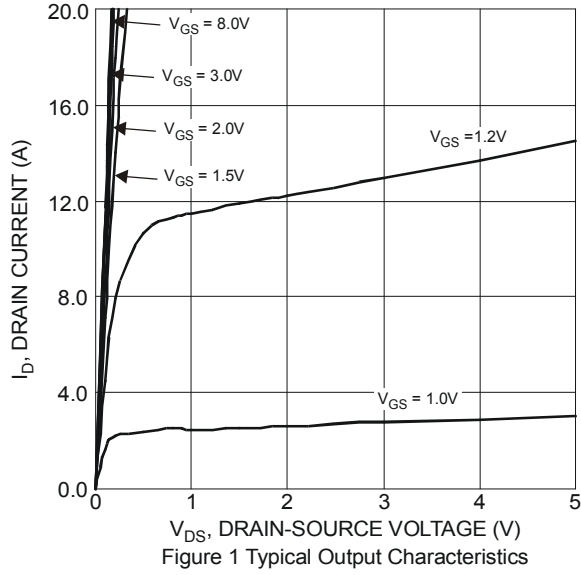
Thermal Characteristics

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	T _A = +25°C	P _D	0.68	W
	T _A = +70°C		0.4	
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	R _{θJA}	160	°C/W
	t < 10s		115	
Total Power Dissipation (Note 6)	T _A = +25°C	P _D	1.2	W
	T _A = +70°C		0.83	
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	R _{θJA}	96	°C/W
	t < 10s		68	
Thermal Resistance, Junction to Case (Note 6)		R _{θJC}	18	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	12	—	—	V	V _{GS} = 0V, I _D = 250µA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	µA	V _{DS} = 12V, V _{GS} = 0V
Gate-Body Leakage	I _{GSS}	—	—	±2	µA	V _{GS} = ±8V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(th)}	0.35	0.53	0.8	V	V _{DS} = V _{GS} , I _D = 250µA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	7	10	mΩ	V _{GS} = 4.5V, I _D = 9.7A
		—	8	12		V _{GS} = 2.5V, I _D = 9A
		—	10	14		V _{GS} = 1.8V, I _D = 8.1A
		—	14	18		V _{GS} = 1.5V, I _D = 4.5A
		—	28	41		V _{GS} = 1.2V, I _D = 2.4A
Forward Transfer Admittance	Y _{fs}	—	28	—	S	V _{DS} = 4V, I _D = 9.7A
Diode Forward Voltage	V _{SD}	—	0.8	1.2	V	V _{GS} = 0V, I _S = 10A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	—	2426	—	pF	V _{DS} = 10V, V _{GS} = 0V, f = 1MHz
Output Capacitance	C _{oss}	—	396	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	375	—	pF	
Gate Resistance	R _g	—	1.1	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge (V _{GS} = 8V)	Q _g	—	50.6	—	nC	V _{DS} = 4V, I _D = 10A
Total Gate Charge (V _{GS} = 4.5V)	Q _g	—	27.3	—		
Gate-Source Charge	Q _{gs}	—	3.4	—		
Gate-Drain Charge	Q _{gd}	—	5.2	—		
Turn-On Delay Time	t _{D(ON)}	—	7.6	—	ns	V _{DD} = 4V, V _{GEN} = 5V, I _D = 10A, R _G = 1Ω, R _L = 0.4Ω
Turn-Off Delay Time	t _{D(OFF)}	—	22.2	—	ns	
Turn-On Rise Time	t _r	—	57.6	—	ns	
Turn-Off Fall Time	t _f	—	16.8	—	ns	

- Notes:
- Device mounted on FR-4 PCB with minimum recommended pad layout, single sided. The power dissipation P_D is based on t < 10s R_{θJA}.
 - Device mounted on 1" x 1" FR-4 PCB with high coverage 2 oz. Copper, single sided. The power dissipation P_D is based on t < 10s R_{θJA}.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to production testing.



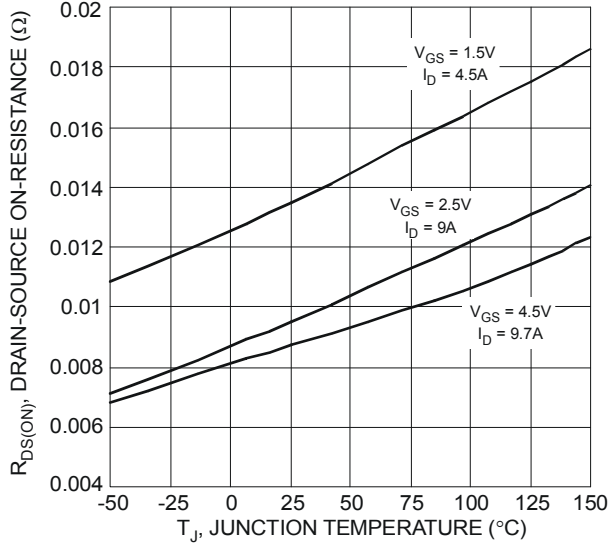


Figure 7 On-Resistance Variation with Temperature

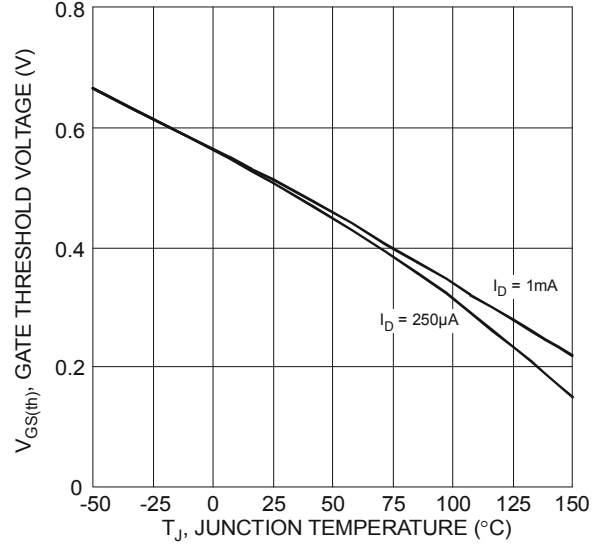


Figure 8 Gate Threshold Variation vs. Ambient Temperature

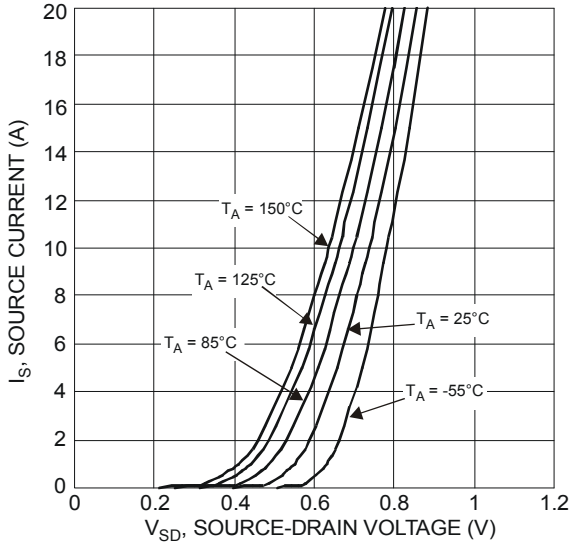


Figure 9 Diode Forward Voltage vs. Current

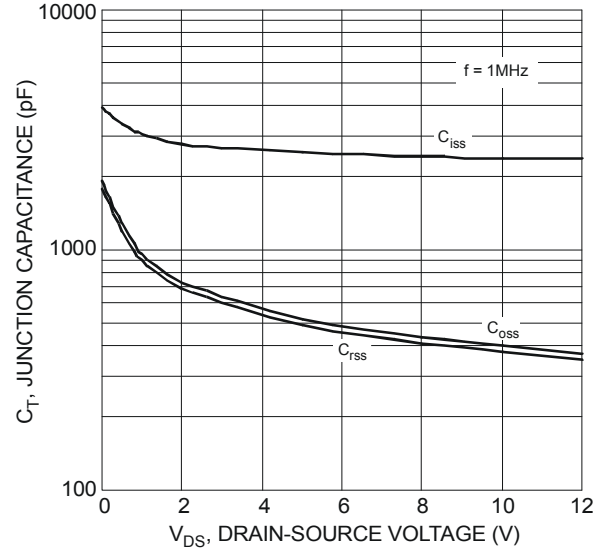


Figure 10 Typical Junction Capacitance

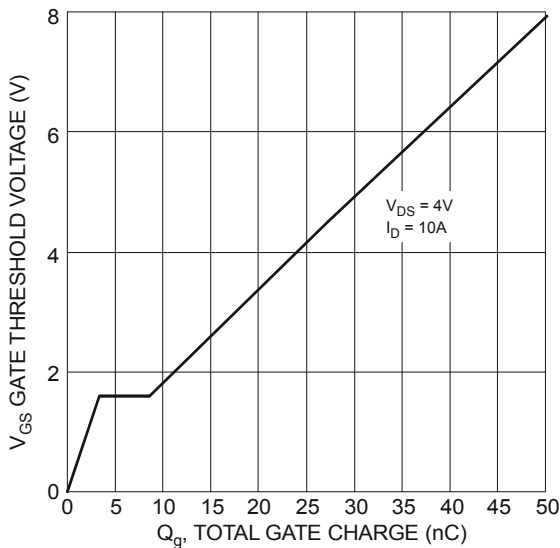


Figure 11 Gate Charge

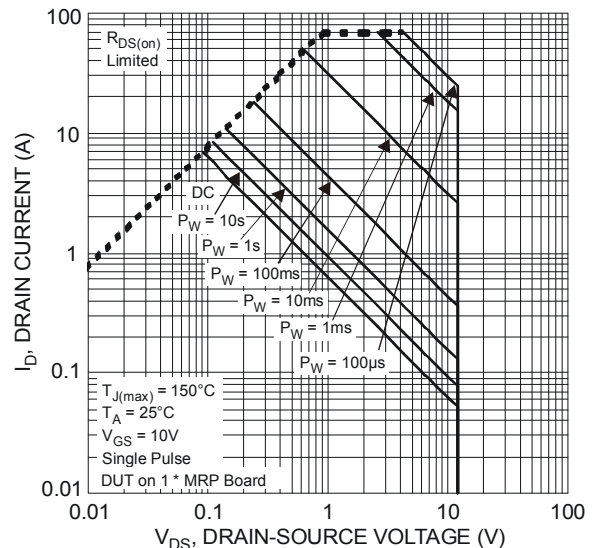
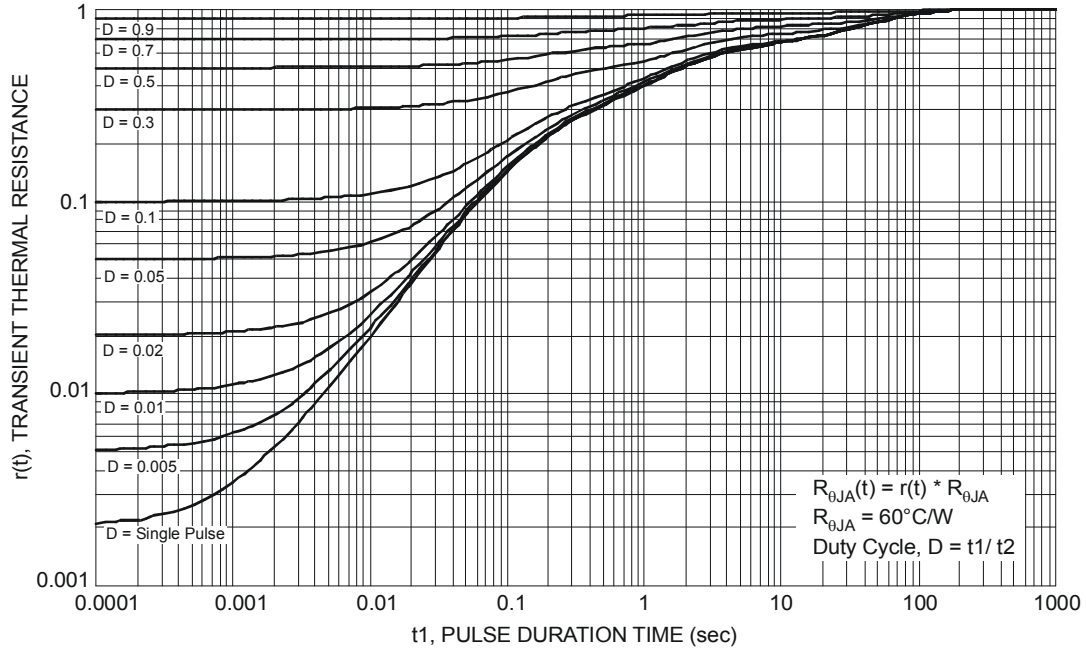
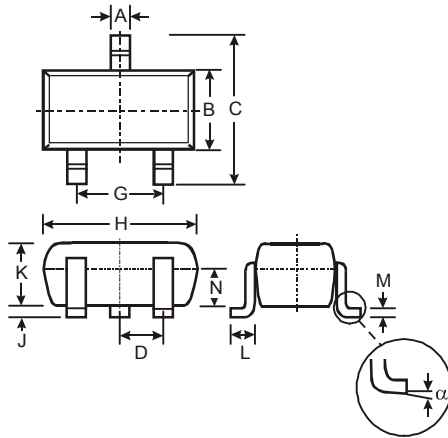


Figure 12 SOA, Safe Operation Area



Package Outline Dimensions

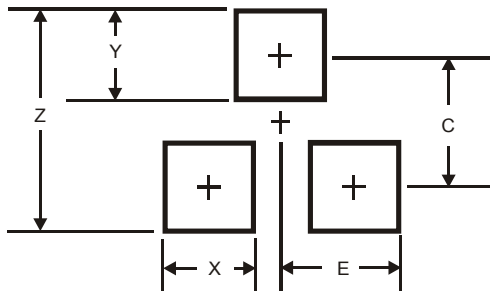
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SC59			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	-	-	0.95
G	-	-	1.90
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
N	0.70	0.80	0.75
α	0°	8°	-
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	3.4
X	0.8
Y	1.0
C	2.4
E	1.35

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